

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

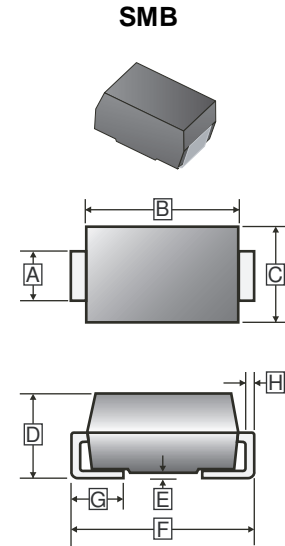
- High Current Capability
- Extremely Low Thermal Resistance
- For Surface Mount Application
- Higher Temp Soldering
- Low Reverse Current

MECHANICAL DATA

- Case: Molded Plastic
- Epoxy: UL 94V-0 Rate Flame Retardant
- Polarity: Color Band Denotes Cathode End
- Mounting Position: Any

PACKAGE INFORMATION

Package	MPQ	Leader Size
SMB	3K	13 inch



ORDER INFORMATION

Part Number	Type
SEF112B-C	Lead (Pb)-free and Halogen-free

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	1.85	2.20	E	-	0.203
B	4.00	4.75	F	5.08	5.59
C	3.25	3.94	G	0.75	1.52
D	1.99	2.61	H	0.15	0.31

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load de-rate current by 20%.)

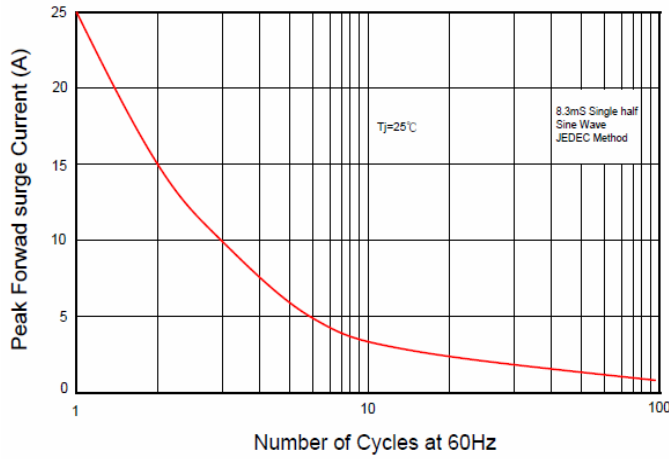
Parameter	Symbol	Ratings	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	1200	V
RMS Voltage	V_{RMS}	850	V
Average Forward Current	$I_{F(AV)}$	1	A
Peak Forward Current @8.3ms, single half sine wave	I_{FSM}	25	A
Maximum Instantaneous Forward Voltage @ $I_F=1A$	V_F	$T_A=25^\circ C$	1.9 (Typ. 1.6)
		$T_A=125^\circ C$	1.6 (Typ. 1.2)
Maximum Reverse Current @ $V_R=1200V$	I_R	$T_J=25^\circ C$	5
		$T_J=125^\circ C$	50
Typical Junction Capacitance ²	C_J	4.5	pF
Typical Thermal Resistance ³	$R_{\theta JA}$	80	°C/W
Reverse Recovery Time ¹	T_{RR}	75 (Typ. 60)	nS
Operating Temperature Range	T_J	-50~150	°C
Storage temperature	T_{STG}	-65~150	°C

Notes:

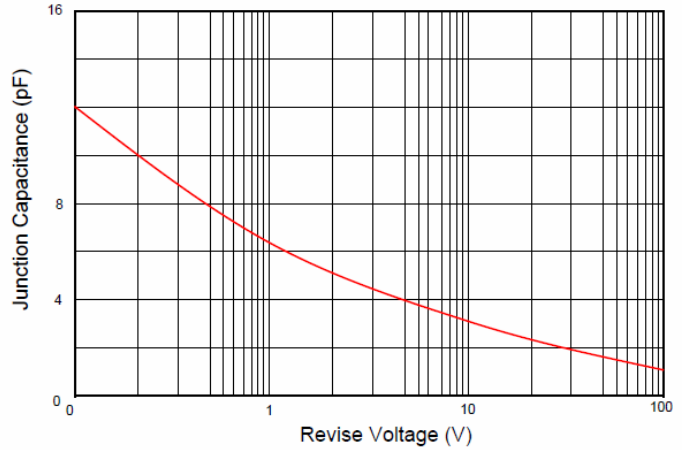
1. Measured with $I_F=0.5A$, $I_{RR}=0.25A$, $I_R=1A$.
2. Measured at 1MHz and applied reverse voltage of 5V D.C.
3. Thermal Resistance Junction to Ambient. Printed circuit board FR4 copper pad 1x1cm, 35um thickness.

RATINGS AND CHARACTERISTIC CURVES

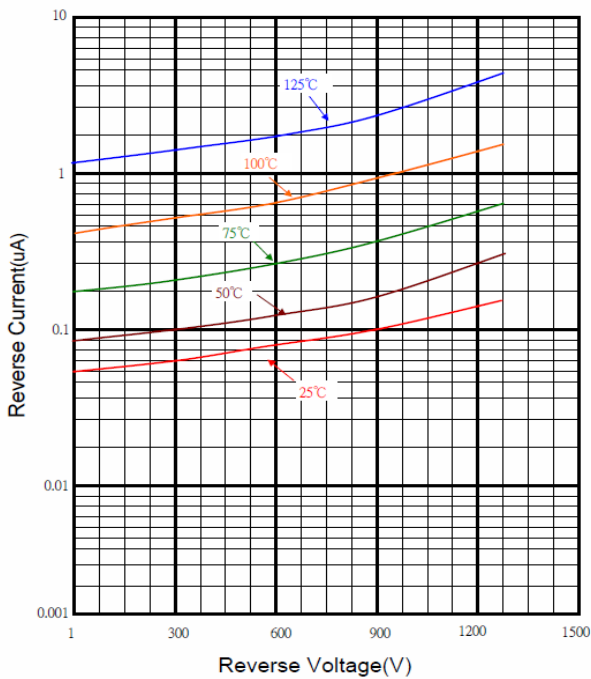
Maximum Non- Repetitive Forward Surge Current



Typical Junction Capacitance



Typical Reverse Characteristic



Typical Forward Characteristic

